



FEATURES

- Transient protection for high-speed data lines
IEC 61000-4-2(ESD) $\pm 25\text{KV}$ (Air)
 $\pm 20\text{KV}$ (Contact)
IEC 61000-4-4(EFT)40A(5/50ns)
Cable Discharge Event(CDE)
- Package optimized for high-speed lines
- Small package(2.1mm*2.3mm*1.0mm)
- Protects four data lines and one Vcc line
- Low capacitance: 0.20pF (I/O to I/O)
- Low leakage current
- Low clamping voltage
- Each I/O pin can withstand over 1000 ESD strikes for $\pm 8\text{KV}$ contact discharge

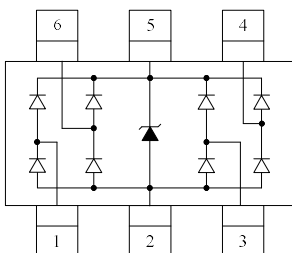
MACHANICAL DATA

- SOT-363 package
- Flammability Rating: UL 94V-0
- Terminal: Matte tin plated.
- Packaging: Tape and Reel
- High temperature soldering guaranteed: $260^{\circ}\text{C}/10\text{s}$
- Reel size: 7 inch

ORDERING INFORMATION

- Device: LXE363F5V0U
- Package: SOT-363
- Marking: F54
- Material: Halogen free
- Packing: Tape & Reel
- Quantity per reel: 3,000pcs

PIN CONFIGURATION



DESCRIPTION

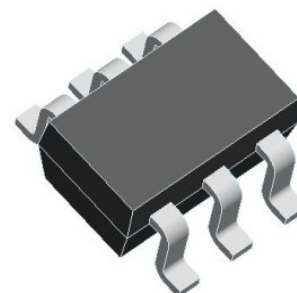
LXE363F5V0U is an ultra-low capacitance Transient Voltage Suppressor (TVS) designed to protection for high-speed data interfaces. With typical capacitance of 0.20pF (I/O to I/O) only, LXE363F5V0U is designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4($\pm 15\text{KV}$ air, $\pm 8\text{KV}$ contact discharge), IEC61000-4-4 (electrical fast transient-EFT) (40A, 5/50ns),very fast charged device model (CDM) ESD and cable discharge event (CDE), etc.

LXE363F5V0U uses small SOT-363 package. Each LXE363F5V0U device can protect four high-speed data lines one Vcc line. The combined features of ultra-low capacitance, small size and high ESD robustness make LXE363F5V0U ideal for high-speed data ports and high-frequency lines (e.g., HDMI & DVI) applications. The low clamping voltage of the LXE363F5V0U guarantees a minimum stress on the protected IC.

APPLICATIONS

- Serial ATA
- MDDI Ports
- USB 2.0/3.0 Power and Data Line Protection
- Display Ports
- High Definition Multi-Media Interface (HDMI)
- Digital Visual Interface (DVI)

PACKAGE OUTLINE





ABSOLUTE MAXIMUM RATING

Parameter	Symbol	Value	Units
Peak Pulse Power (8/20 μ s)	P _{PP}	60	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	\pm 25	kV
ESD per IEC 61000-4-2 (Contact)		\pm 20	
Operating Temperature	T _{OPT}	-55/+125	$^{\circ}$ C
Storage Temperature	T _{STG}	-55/+150	$^{\circ}$ C

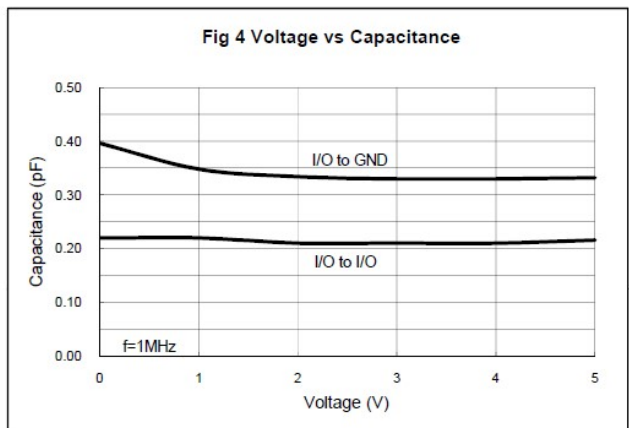
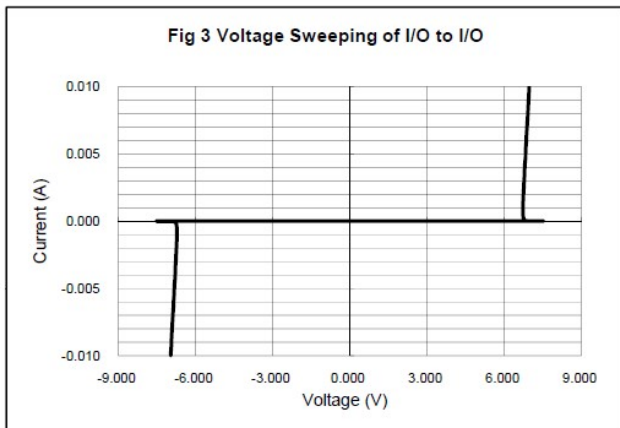
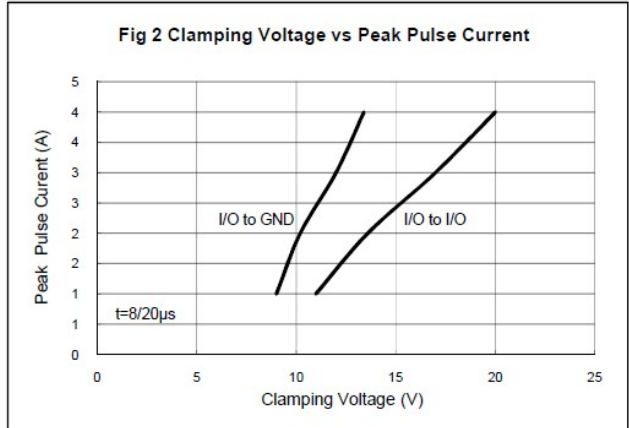
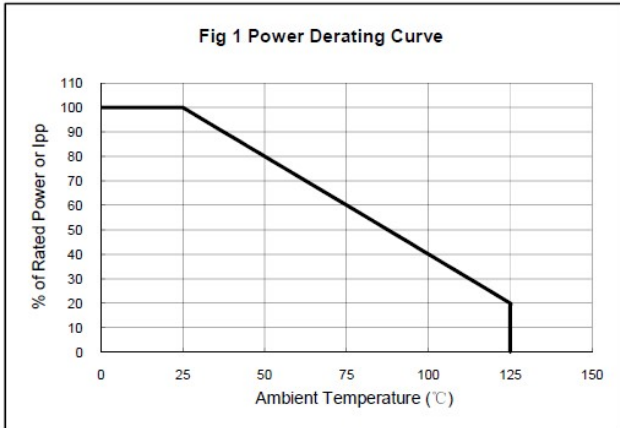
ELECTRICAL CHARACTERISTICS (T_{amb}=25 $^{\circ}$ C)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V _{RWM}	Reverse Working Voltage	Any I/O pin to GND			5.0	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA Any I/O pin to GND	6.0		9.0	V
I _R	Reverse Leakage Current	V _{RWM} = 5V Any I/O pin to GND			1.0	μ A
V _C	Clamping Voltage	I _{PP} = 1A, t _p =8/20 μ s Any I/O pin to GND			10	V
		I _{PP} = 4A, t _p =8/20 μ s Any I/O pin to GND			15	V
		I _{PP} = 8A, t _p =8/20 μ s V _{cc} pin to GND			15	V
C _{ESD}	Parasitic Capacitance	V _R = 0V, f = 1MHz Between I/O and I/O		0.20	0.30	pF
		V _R = 0V, f = 1MHz Between I/O and GND		0.45	0.50	pF
		V _R = 0V, f = 1MHz Between V _{cc} and GND		0.80		pF

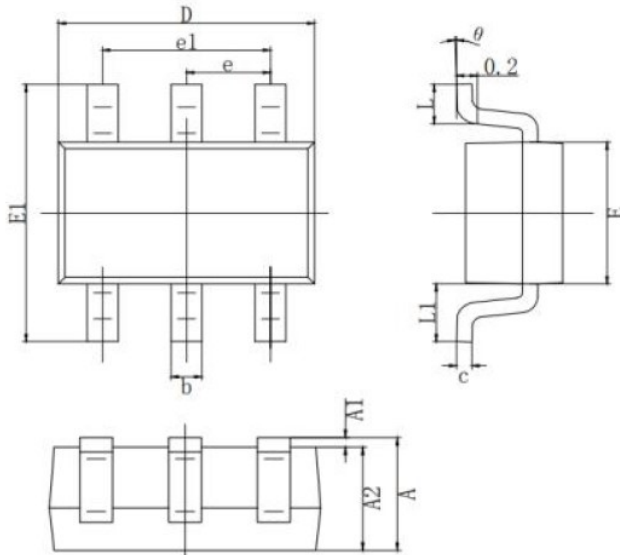
Note: I/O Pins are pin 1,3,4,6. Pin 5 is V_{cc}. Pin 2 is GND.



ELECTRICAL CHARACTERISTICS CURVE

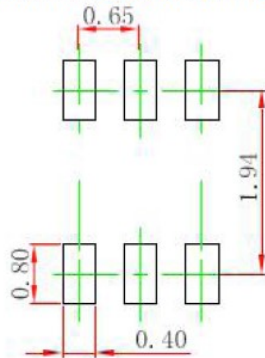


SOT-363 PACKAGE OUTLINE DIMENSIONS



SYMBOL	MILLIMETER	
	MIN	MAX
A	0.900	1.100
A1	0.000	0.100
A2	0.900	1.000
b	0.150	0.350
c	0.080	0.150
D	2.000	2.200
E	1.150	1.350
E1	2.150	2.450
e	0.650 TYP.	
e1	1.200	1.400
L	0.525 REF.	
L1	0.260	0.460
θ	0°	8°

Recommended land dimensions for SOT-363. Electrode patterns for PCBs



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05mm.
 3. The pad layout is for reference purposes only.